



## Product Change Notification: DSNO-01SOPR415

**Date:**

03-Nov-2025

**Product Category:**

Ethernet Phys

**Notification Subject:**

CCB 7393.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for KSZ8081RNACA, KSZ8081RNACA-TR, KSZ8081RNAIA-TR, KSZ8081RNDCA-TR, KSZ8081RNDIA-TR, KSZ8091RNACA-TR, KSZ8091RNAIA-TR, KSZ8091RNDCA-TR, KSZ8091RNDIA-TR, SPNY801142-TR, SPNY801143-TR, SPNY801147-TR, SPNZ801128-TR, SPNZ801143 and SPNZ801143-TR catalog part numbers (CPN) available in 24L VQFN (4x4x0.9mm) package.

**Affected CPNs:**

[\*\*DSNO-01SOPR415\\_Affected\\_CPN\\_11032025.pdf\*\*](#)  
[\*\*DSNO-01SOPR415\\_Affected\\_CPN\\_11032025.csv\*\*](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for KSZ8081RNACA, KSZ8081RNACA-TR, KSZ8081RNAIA-TR, KSZ8081RNDCA-TR, KSZ8081RNDIA-TR, KSZ8091RNACA-TR, KSZ8091RNAIA-TR, KSZ8091RNDCA-TR, KSZ8091RNDIA-TR, SPNY801142-TR, SPNY801143-TR, SPNY801147-TR, SPNZ801128-TR, SPNZ801143 and SPNZ801143-TR catalog part numbers (CPN) available in 24L VQFN (4x4x0.9mm) package.

**Pre and Post Summary Changes:**

	<b>Pre Change</b>	<b>Post Change</b>	<b>Change (Yes/No)</b>

<b>Assembly Site</b>	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
<b>Wire Material</b>	Au	CuPdAu	Yes
<b>Die Attach Material</b>	QMI519	QMI519	No
<b>Molding Compound Material</b>	G700LTD	G700LTD	No
<b>Lead-Frame Material</b>	A194	A194	No

Note: The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #[CENO-16EGCZ399](#).

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 23 January 2026 (date code: 2604)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

	November 2025					>	January 2026				
Work Week	45	46	47	48	49		01	02	03	04	05
<b>Qual Report Availability</b>	X										
<b>Final PCN Issue Date</b>	X										
<b>Estimated Implementation Date</b>										X	

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_{PCN Number}\_Qual\_Report.

**Revision History:** November 03, 2025: Issued final notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

[\*\*PCN\\_DSNO-01SOPR415\\_Qual\\_Report.pdf\*\*](#)

Please contact your local [\*\*Microchip sales office\*\*](#) with questions or concerns regarding this notification.

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